





Drawing No.	*Rev.	Date	Page
BF5A04GA-NPD	C	2022/05/09	1/3

APPROVAL SHEET

Part No: **BF5A04GA-NPD**

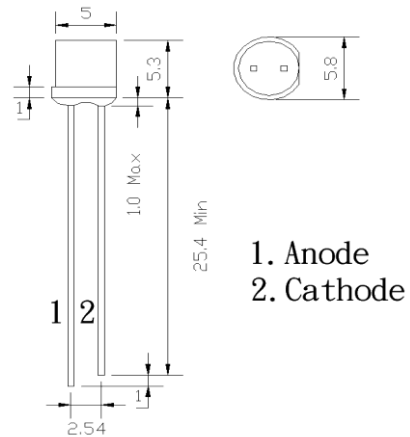
NOTE : Green Part

MAKER			CUSTOMER	
				
R&D	QA	Sales	Checked	Approved
				

Prepared	Checked	Approved
Rachel Lee	Sky Lin	Kenneth Wu

DESCRIPTION:

Device Type : BF5A04GA-NPD
 Dice Material : Silicon
 Lens Color : Water Clear
 Lens Dimension : 5 mm



All epoxy resin dimension are in millimeter tolerance is $\pm 0.2\text{mm}$

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating.	Unit
Power Dissipation	PC	100	mW
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstr	-40 ~ +100	°C
Solder DIP (MAX. 5 seconds, 1.6mm from body) Temperature 260°C			

Electrical and Optical Characteristics at Ta=25°C

Description	Symbol	Condition	Min.	Typ.	Max.	Unit
Range of Spectral Bandwidth	Wp	-	400	-	670	nm
Peak Sensitivity Wavelength	Wp	-	-	630	-	nm
Reverse Light Current	IL	VR=5V.Ee=1mW/ cm ²	-	10	-	uA
Reverse Dark Current	ID	VR =10V.Ee=0mW/ cm ²	-	2	10	nA
Reverse breakdown voltage	VBR	IR=100uA.Ee=0mW/ cm ²	35	-	-	V
Open-Circuit Voltage	Voc	Ee=5mW/cm ² λp=940nm	-	0.35	-	V
Short- Circuit Current	Isc	Ee=1mW/cm ² λp=940nm	-	40	-	μA
Rise Time/ Fall Time	tr/ tf	VR=10V RL=1KΩ	-	45 / 45	-	ns
Total Capacitance	Ct	VR =5V Ee=0mW/cm ² f=1MHz	-	25	-	pF

Note: 1.The lead should be formed up to 5mm from the body of device without forming stress.
 2. Soldering shall be performed after lead forming.
 3. All dimensions are in millimeters

LED LAMP Technical Data

Typical Optical-Electrical Characteristic Curves

Collector Power Dissipation vs Ambient Temperature

